



Ordering Information

Part number : **MBE71-abc x y**

• **abc**: The type of Processor

(Dual Core-A72 @2.0Ghz,+ Quad Core-A53 @ 1.5Ghz)

“R39” 0 ~ 70°C.

“K39” -20 ~ 70°C.

• **x**: The DDR3 Memory size on board

“1” 1GB of DDR3.

“2” 2GB of DDR3.

• **y**: The eMMC size on board

“8” 8GB of eMMC.

“F” 16GB of eMMC.

Features

• Processor:

- High performance Dual Cortex-A72 @2.0Ghz + Quad Cortex-A53 @ 1.5Ghz

• System Memory & Storage:

- 1GB /2GB/4GB DDR3-1066 SDRAM onboard
- 8GB/16GB eMMC Flash memory

• Multi-Media Processor:

- ARM Mail-T860MP4 (GPU), AFBC supported
- Provides OpenGL ES1.1/2.0/3.0/3.1, OpenVG1.1, OpenCL, DX11
- Video Decoder:
H.264/H.265, 10bit, up to 4Kx2K@60fps,
VP9, 8bit, up to 4Kx2K@60fps,
MPEG-4/MPEG-2/VP8 up to 1080p@60fps
- Video Encoder:
H.264/MVC/VP8 encoders by 1080p@30fps

• External I/O (On board side):

- 1 x Gigabit Ethernet port
- 1 x HDMI® V2.0, 4Kx2K @60fps, HDCP2.x
- 1 x USB 3.0, type A port
- 2 x USB 2.0, type A port
- 1 x Micro SD/SDHC card slot
- 1 x Power Jack

• Internal I/O

- eDP 1.3, 2 lane , 1080p@60fps, ZIF
- LCD Backlight control wafer
- PCAP touch panel wafer
- WLAN, 802.11 (a/b/g/n/ac, 2Tx2R) + Bluetooth (4.1 LE)
- USB 2.0 (x 3) expansion header
- Audio Combo Header, (Mic_in,Line_out, Spk_out, HP_out, SPDIF)
- Keys, DIO extension header
- MIPI-CSI, ZIF connector (option)
- MEMS Combo header (option)
- RS232 console wafer

• Power supply:

- Adaptor DC12V/ 24V
- PD board for PoE IEEE 802.3at (option)

• Operation Temperature:

Commercial version: 0°C to 70°C
Industrial version :-20°C to 70°C

• Operating System:

- Android 7.1/ 8
- Linux 4.4.154 _Debian 9.0 (Stretch)

www.forenex.com.tw

e_mail: sales@forenex.com.tw